

# 80V N-Channel Split Gate MOSFET

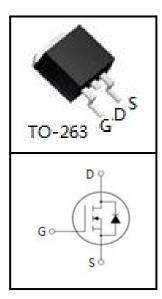
#### **FEATURES**

- Trench Power MOSFET Technology
- Low Rds(ON)
- Low Gate Charge
- Optimized For Fast-switching Applications

#### **APPLICATIONS**

- DC/DC Converter
- Ideal for high-frequency switching and synchronous rectification





Device Marking and Package Information			
Device	Package	Marking	
CSB08N6P5	TO-263	CSB08N6P5	

Absolute Maximum Ratings at	Ratings at T <sub>j</sub> = 25°C unless otherwise noted			
Parameter		Symbol	Value	Unit
Drain-Source Voltage (V <sub>GS</sub> = 0V)		$V_{DSS}$	80	V
Continuous Drain Current T <sub>C</sub> = 25°C	(note1)	,	130	Α
Continuous Drain Current T <sub>C</sub> = 100°C	(note1)	I <sub>D</sub>	100	A
Pulsed Drain Current	(note2)	I <sub>DM</sub>	280	Α
Gate Source Voltage		V <sub>GSS</sub>	±20	V
Single Pulse Avalanche Energy	(note3)	E <sub>AS</sub>	100	mJ
Power Dissipation T <sub>C</sub> = 25°C	(note4)	P <sub>D</sub>	56	W
Operating Junction and Storage Temperatu	re Range	T <sub>J</sub> , T <sub>stg</sub>	-55~+150	°C

Thermal Characteristics			
Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case	R <sub>eJc</sub>	0.4	°C/W
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	62.5	] <sup>-</sup> C/W



Electrical Characteristics T <sub>j</sub>	= 25°C ur	nless otherwise specified				
Daysonstan			Value			
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_{D} = 250\mu A$	80			V
Zero Gate Voltage Drain Current		$V_{DS} = 64V, V_{GS} = 0V, T_{J} = 25^{\circ}C$			1	uA
Zero Gate Voltage Drain Gurrent	I <sub>DSS</sub>	V <sub>DS</sub> = 64V, V <sub>GS</sub> = 0V, T <sub>J</sub> = 100°C			5	uA
Gate-Source Leakage	I <sub>GSS</sub>	$V_{GS} = \pm 20V$			±100	nA
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1.2		2.5	V
Dunin Course On Besistance (note2)		V <sub>GS</sub> = 10V, I <sub>D</sub> = 30A		4.5	6.5	mΩ
Drain-Source On-Resistance (note2)	$R_{DS(on)}$	V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 20A		6.5	8.5	mΩ
		Dynamic				
Input Capacitance	C <sub>iss</sub>	\/ - 0\/		2900		
Output Capacitance	$C_{oss}$			420		pF
Reverse Transfer Capacitance	C <sub>rss</sub>	f = 1.0MHz		40		
Total Gate Charge (4.5V)	$Q_g$			40		
Gate-Source Charge	$Q_{gs}$	$V_{DS} = 40V, I_{D} = 15A,$ $V_{GS} = 10V$		7.2		nC
Gate-Drain Charge	$Q_{gd}$			6.5		
Turn-on Delay Time	t <sub>d(on)</sub>			8.3		
Turn-on Rise Time	t <sub>r</sub>	V <sub>DS</sub> = 40V, I <sub>D</sub> = 15A		4.2		
Turn-off Delay Time	$t_{d(off)}$	$R_{\rm G} = 3\Omega$		36		ns
Turn-off Fall Time	t <sub>f</sub>			6.9		
	В	ody Diode Characteristics				
Source-Drain Current(Body Diode)	Is				130	_
Pulsed Source-Drain Current(Body Diode)	I <sub>SDM</sub>				280	Α
Body Diode Voltage	$V_{SD}$	$T_J = 25^{\circ}C$ , $I_{SD} = 1A$ , $V_{GS} = 0V$			1.2	V

#### **Notes**

- 1. The data tested by surface mounted on a 1 inch2 FR-4 board with 2OZ copper.
- 2. The data tested by pulsed , pulse width  $\leq\!300\text{us}$  , duty cycle  $\leq\!2\%$
- 3. The EAS data shows Max. rating . The test condition is VDD =25V,VGS =10V,L=0.1mH  $\,$
- 4. The power dissipation is limited by 175°C junction temperature
- 5. The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation.



### **Typical Characteristics** $T_J = 25^{\circ}\text{C}$ , unless otherwise noted

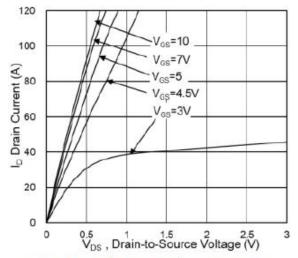


Fig.1 Typical Output Characteristics

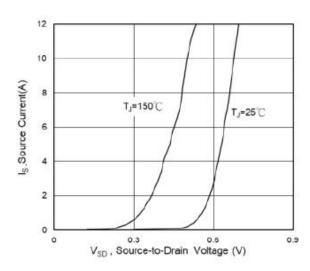


Fig.3 Source Drain Forward Characteristics

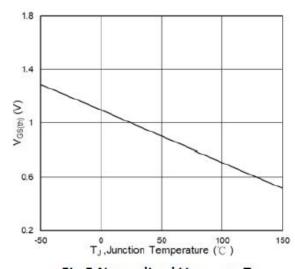


Fig.5 Normalized V<sub>GS(th)</sub> vs. T<sub>J</sub>

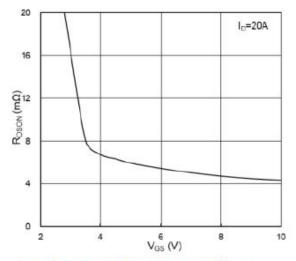


Fig.2 On-Resistance vs. G-S Voltage

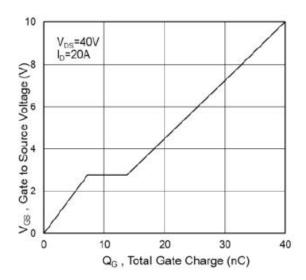


Fig.4 Gate-Charge Characteristics

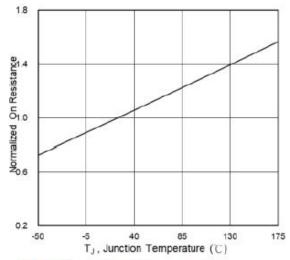
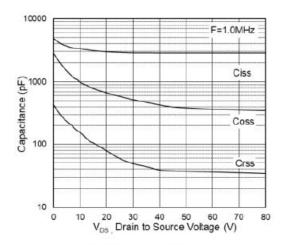


Fig.6 Normalized RDSON vs. TJ



## **Typical Characteristics** $T_J = 25^{\circ}C$ , unless otherwise noted



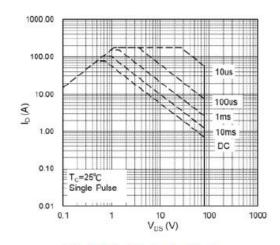


Fig.7 Capacitance

Fig.8 Safe Operating Area

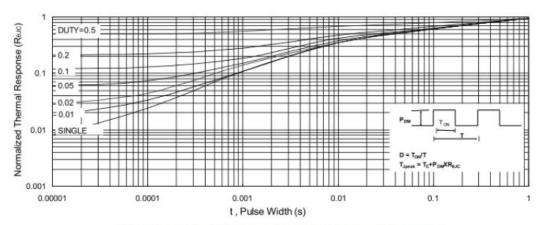


Fig.9 Normalized Maximum Transient Thermal Impedance



Figure A: Gate Charge Test Circuit and Waveform

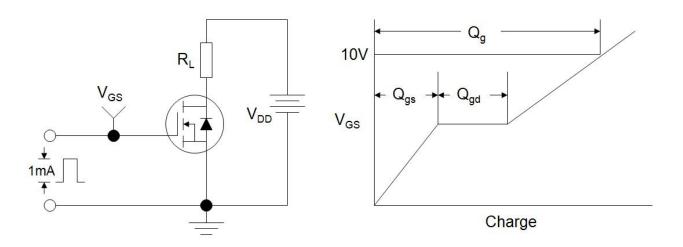


Figure B: Resistive Switching Test Circuit and Waveform

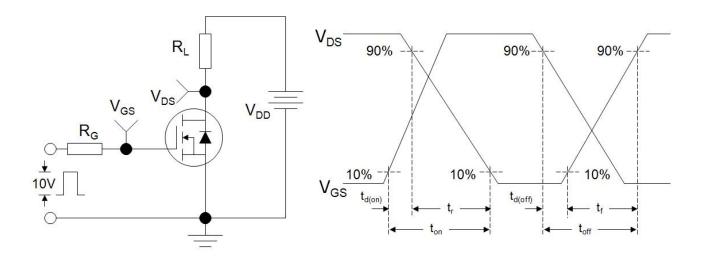
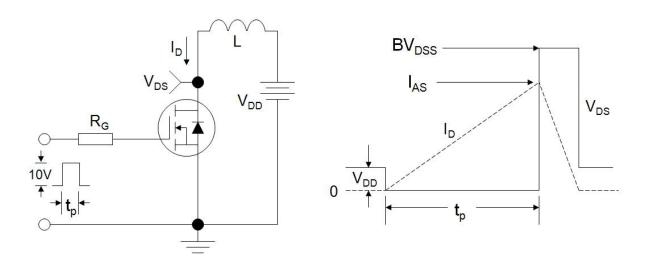
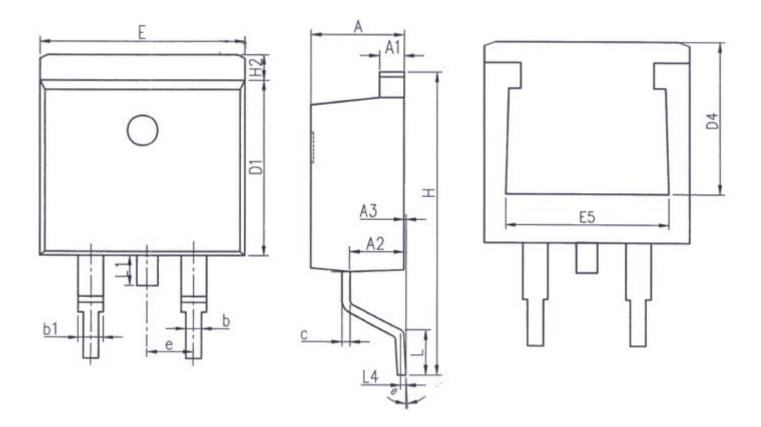


Figure C: Unclamped Inductive Switching Test Circuit and Waveform





**TO-263** 



l	Jnit: mm	n
Symbol	Min.	Max.
E	9.86	10.36
E5	7.06	<u> 44</u>
е	2. 54	4BSC
Н	14. 70	15.50
H2	1.07	1.47
L	2.00	2.60
L1	1. 40	1.70
L4	0. 25	BSC
θ	0°	9°

Unit: mm		
Symbol	Min.	Max.
Α	4. 37	4. 77
A1	1. 22	1.42
A2	2.49	2. 89
A3	0.00	0. 25
b	0.70	0.96
b1	1.17	1.47
С	0.30	0.53
D1	8.50	8. 90
D4	6.60	s <b>–</b>



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